Quad Bus Driver/Receiver with Transmit and Receiver Latches

Description

The MC10H334 is a Quad Bus Driver/Receiver with transmit and receiver latches. When disabled, (\overline{OE} = high) the bus outputs will fall to -2.0 V. Data to be transmitted or received is passed through its respective latch when the respective latch enable (\overline{DLE} and \overline{RLE}) is at a low level. Information is latched on the positive transition of \overline{DLE} and \overline{RLE} . The parameters specified are with 25 Ω loading on the bus drivers and 50 Ω loads on the receivers.

Features

- Propagation Delay, 1.6 ns Typical Data-to-Output
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10KTM Compatible
- Pb-Free Packages are Available*

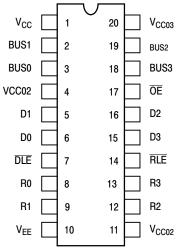


Figure 1. Pin Assignment

Pin assignment is for Dual-in-Line Package.



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MARKING DIAGRAMS*

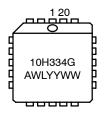




CDIP-20 L SUFFIX CASE 732



PLLC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot
 YY = Year
 WW = Work Week
 G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

^{*}For additional marking information, refer to Application Note AND8002/D.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Table 1. MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
V _{EE}	Power Supply (V _{CC} = 0)	-8.0 to 0	Vdc
VI	Input Voltage (V _{CC} = 0)	0 to V _{EE}	Vdc
l _{out}	Output Current - Continuous - Surge	50 100	mA
T _A	Operating Temperature Range	0 to +75	°C
T _{stg}	Storage Temperature Range - Plastic - Ceramic	-55 to +150 -55 to +165	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Table 2. ELECTRICAL CHARACTERISTICS ($V_{EE} = -5.2 \text{ V} \pm 5\%$) (Note 1)

		0)°	25	5°	7	75°	
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
Ι _Ε	Power Supply Current	-	161	-	161	-	161	mA
I _{inH}	Input Current High Pins 5,6,15,16 Pins 7,14 Pin 17	- - -	397 460 520	- - -	273 297 357	- - -	273 297 357	μΑ
I _{inL}	Input Current Low	0.5	_	0.5	_	0.3	_	μΑ
V _{OH}	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
V _{OL}	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
V _{IH}	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V _{IL}	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

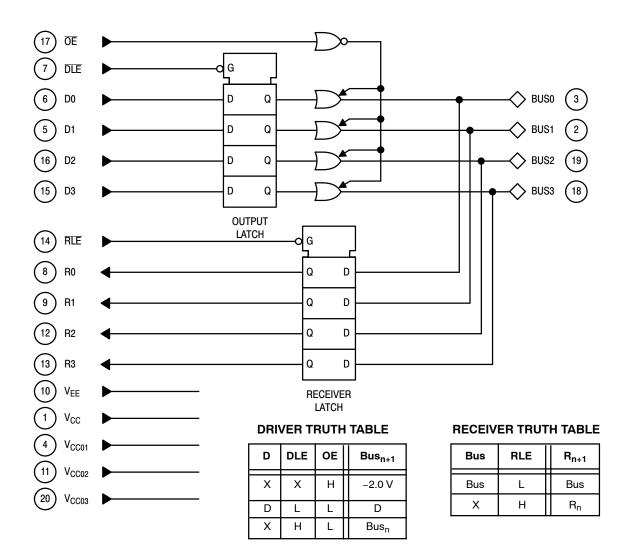
Each MECL 10H™ series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained. Receiver outputs are terminated through a 50 Ω resistor to −2.0 V dc. Bus outputs are terminated through a 25 Ω resistor to −2.0 Vdc.

Table 3. AC PARAMETERS

		0	0	2	5°	7	75°	
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
t _{pd}	Propagation Delay							ns
	Data-to-Bus Output	0.5	2.5	0.5	2.5	0.5	2.5	
	DLE-to-Bus Output	1.0	2.7	1.0	2.7	1.0	2.7	
	OE-to-Bus Output	0.5	2.5	0.5	2.5	0.5	2.5	
	Bus-to-R0	0.5	1.9	0.5	1.9	0.5	1.9	
	RLE-to-R0	0.5	2.1	0.5	2.1	0.5	2.1	
	Data-to-Receiver R0	1.0	3.8	1.0	3.8	1.0	3.8	
t _r	Rise Time	0.5	2.2	0.5	2.2	0.5	2.2	ns
t _f	Fall Time	0.5	2.2	0.5	2.2	0.5	2.2	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

LOGIC DIAGRAM



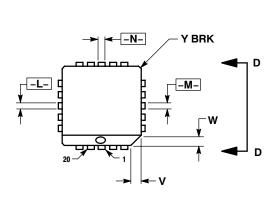
ORDERING INFORMATION

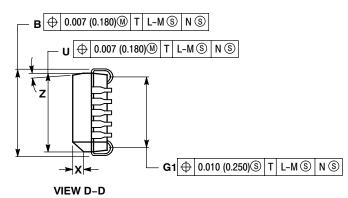
Device	Package	Shipping [†]
MC10H334FN	PLLC-20	46 Units / Rail
MC10H334FNG	PLLC-20 (Pb-Free)	46 Units / Rail
MC10H334FNR2	PLLC-20	500 / Tape & Reel
MC10H334FNR2G	PLLC-20 (Pb-Free)	500 / Tape & Reel
MC10H334L	CDIP-20	19 Unit / Rail

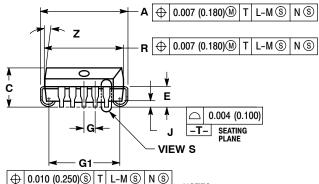
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

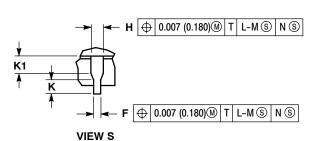
PACKAGE DIMENSIONS

20 LEAD PLLC CASE 775-02 **ISSUE E**









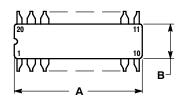
- NOTES:
 1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. DIMENSIONS IN INCHES.
 3. DATUMS -L., -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

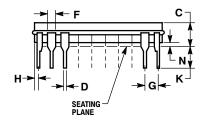
- PARTING LINE.
 4. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM —T-, SEATING PLANE.
 5. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
 6. DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- PLASTIC BODY.
 7. DIMENSION H DOES NOT INCLUDE DAMBAR DIMIENSION H DUES NOT INCLUDE DAMBAR
 PROTRUSION OR INTRUSION. THE DAMBAR
 PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION
 TO BE GREATER THAN 0.037 (0.940). THE DAMBAR
 INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO
 BE SMALLER THAN 0.025 (0.635).

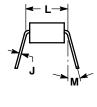
	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Е	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
H	0.026	0.032	0.66	0.81
L	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
C	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Х	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

PACKAGE DIMENSIONS

CDIP-20 L SUFFIX CERAMIC DIP PACKAGE CASE 732-03 ISSUE E







NOTES:

- 1. LEADS WITHIN 0.010 DIAMETER, TRUE POSITION AT SEATING PLANE, AT MAXIMUM MATERIAL CONDITION.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- 3. DIMENSIONS A AND B INCLUDE MENISCUS.

	INCHES		
DIM	MIN	MAX	
Α	0.940	0.990	
В	0.260	0.295	
С	0.150	0.200	
D	0.015	0.022	
F	0.055	0.065	
G	0.100 BSC		
Н	0.020	0.050	
J	0.008	0.012	
K	0.125	0.160	
L	0.300 BSC		
M	0°	15°	
N	0.010	0.040	

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